

40V N-Channel Enhancement Mode MOSFET

Voltage

40 V

Current

240 A

Features

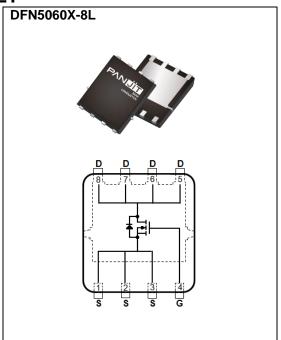
- RDS(ON), VGS@10V, ID@20A<1.38m Ω
- RDS(ON), VGS@4.5V, ID@20A<1.82m Ω
- Excellent FOM
- Logic level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060X-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.087 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	40	- V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C	I _D	240		
	T _C =100°C		170	Α	
Pulsed Drain Current ^(Note 1)	T _C =25°C	I _{DM}	800		
Power Dissipation	T _C =25°C	D-	167	W	
	T _C =100°C	PD	83		
Continuous Drain Current(Note 4)	T _A =25°C	l _D	34	А	
	T _A =70°C		28		
Power Dissipation	T _A =25°C	Po	3.3	W	
	T _A =70°C		2.3		
Single Pulse Avalanche Current ^(Note 5)		I _{AS}	29	Α	
Single Pulse Avalanche Energy ^(Note 5)		E _{AS}	221	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	Rejc	0.9	°C/W	
	Junction to Ambient	$R_{\theta JA}$	45		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA 40		-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =50uA	1.1	1.5	2.3	V	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	1	1.1	1.38	mΩ	
		V _{GS} =4.5V, I _D =20A	ı	1.4	1.82		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)							
Total Gate Charge	Q_g		-	75	98	nC	
Gate-Source Charge	Q_{gs}	V _{DS} =32V, I _D =20A, V _{GS} =10V	-	15	-		
Gate-Drain Charge	Q_{gd}	VGS=1UV	-	10	-		
Input Capacitance	Ciss	\\ O5\\ \\ O\\	ı	4973	6465	pF	
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V,	-	1038	1349		
Reverse Transfer Capacitance	Crss	f=1MHz	-	160	240		
Gate resistance	Rg	f=1MHz	-	1	-	Ω	
Turn-On Delay Time	td _(on)	\/ 00\/ L 00A	-	20	-		
Turn-On Rise Time	tr	V _{DS} =32V, I _D =20A,	-	32	-	ns	
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$	-	68	-		
Turn-Off Fall Time	tf	(Note 2)	-	17	-		
Drain-Source Diode							
Diode Forward Current	Is	Tc=25°C	-	-	240	_	
Pulsed Diode Forward Current	I _{SM}	1c=25 C	-	-	800	А	
Diode Forward Voltage	V_{SD}	I _S =20A, V _{GS} =0V	ı	0.75	1.3	V	
Reverse Recovery Time	Trr	V _{DD} =20V,V _{GS} =0V	-	52	-	ns	
Reverse Recovery Charge	Qrr	Is=20A,dIs/dt=100A/us	-	50	-	nC	

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{BJC}=0.9°C/W, Package limited 120A.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. EAS is calculated based on the condition of L=1mH, IAS=21A, VDD=30V, VGS=10V. 100% test at L=0.5mH, IAS=29A in production.
- 6. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTIC CURVES

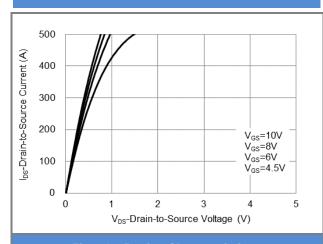


Fig.1 On-Region Characteristics

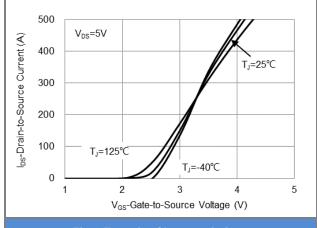


Fig.2 Transfer Characteristics

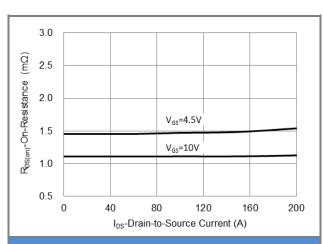


Fig.3 On-Resistance vs. Drain Current

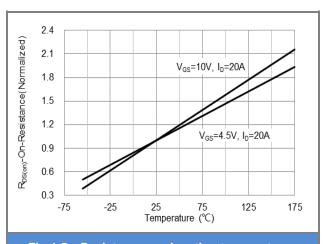


Fig.4 On-Resistance vs. Junction temperature

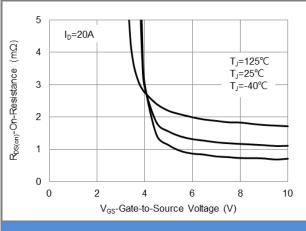


Fig.5 On-Resistance Variation with V_{GS}

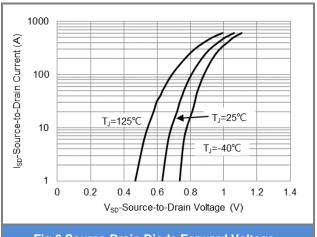


Fig.6 Source-Drain Diode Forward Voltage



TYPICAL CHARACTERISTIC CURVES

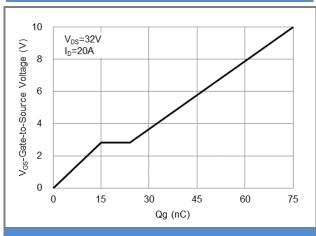


Fig.7 Gate-Charge Characteristics

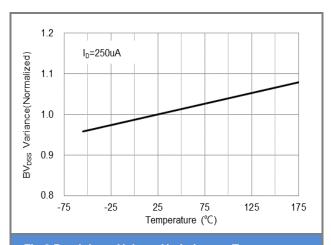


Fig.8 Breakdown Voltage Variation vs. Temperature

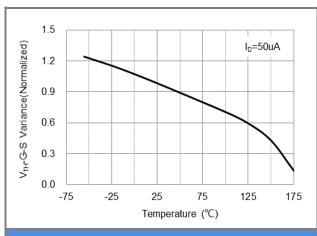


Fig.9 Threshold Voltage Variation with Temperature

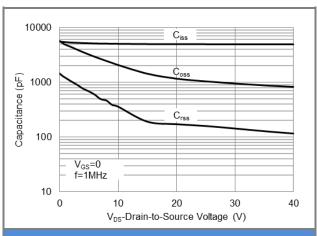
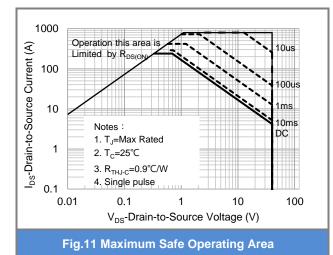
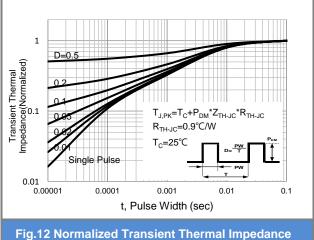


Fig.10 Capacitance vs. Drain-Source Voltage



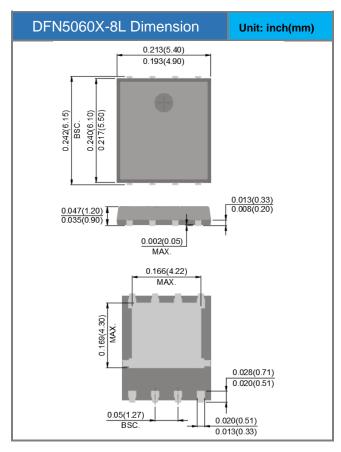


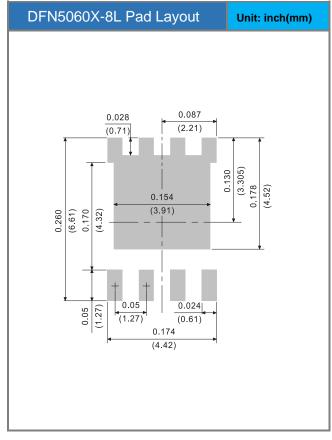


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJQ5540C-AU	DFN5060X-8L	3K pcs / 13" reel	Q5540C	

Packaging Information & Mounting Pad Layout







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